Lattice Semiconductor Corporation - LFEC6E-3Q208I Datasheet



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6100
Total RAM Bits	94208
Number of I/O	147
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec6e-3q208i

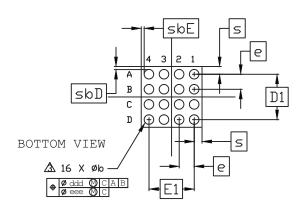
Email: info@E-XFL.COM

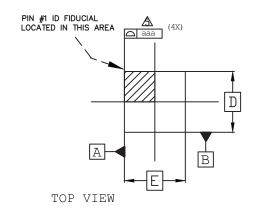
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

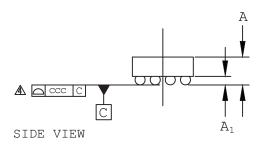


16-Ball WLCS Package Option 2: iCE40 UltraLite™

Dimensions in Millimeters







NOTES:

- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- \triangle PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- $\underline{\mathbb{A}}$ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

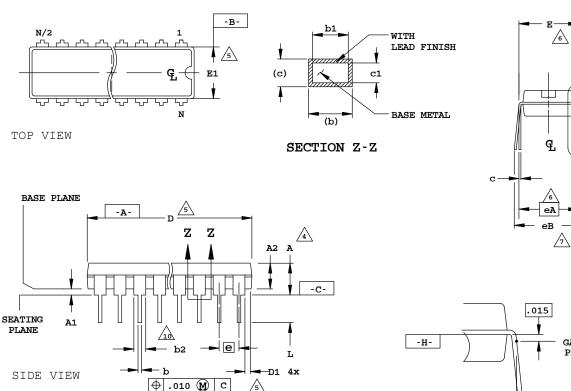
REF.	Min.	Nom.	Max.	
Α	0.413	0.413 0.452 0.493		
A1	0.122 0.152 0.18			
b	0.188	0.218	0.248	
D	1.	409 BS	С	
Ε	1.	409 BS	С	
D1	1.05 BSC			
E1	1.05 BSC			
е	0.35 BSC			
S	- 0.180 -			
sbD	0.067 0.071		0.072	
sbE	0.067 0.071 0.072			
ممم	0.03			
CCC	0.03			
ddd		0.050		
eee		0.015		
'				

SEE DETAIL



20-Pin Plastic DIP Package

Dimensions in Inches



NOTES:

- 1. CONTROLLING DIMENSION: INCH.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
- 3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR
- PROTRUSIONS TO BE .005 MINIMUM. DIMENSIONS A, A1 & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING
- PLANE GAUGE GS-3.
- PLANE GAGE GS-3.

 DIMENSIONS D, D1 AND E1
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010

 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED

 TO BE PERPENDICULAR TO DATUM C-
- 70 BE PERPENDICULAR TO DATOM.

 eB AND eC ARE MEASURED AT THE LEAD TIPS

 with the Leads unconstrained. 8 N IS THE MAXIMUM NUMBER OF LEAD
- POSITIONS.

 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
- 10 b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
- 11 DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

-Н-	GAGE
	→ ← eC

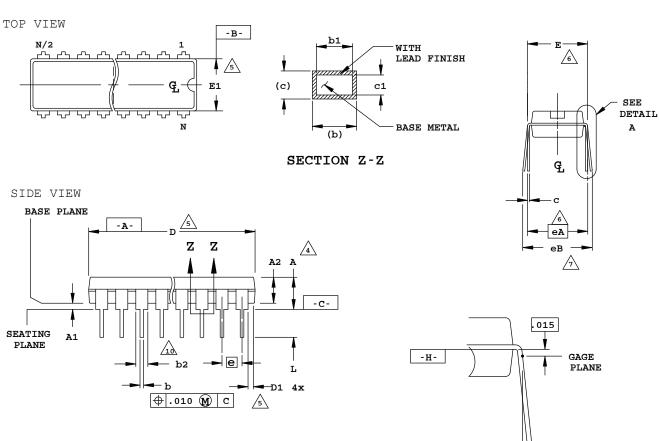
DETAIL A

]	N = 20)		
s Y M B	I	N O T			
o L	MIN.	NOM.	MAX.	TE	
Α	-	ı	.210	4	
A 1	.015	-	-	4	
A 2	.115				
b	.014	.014 .018 .022			
b1	.014	.018	.020		
b2	.045	.060	.070	10	
С	.008	.010	.014		
C1	.008	.008 .010 .01			
D	.980	.980 1.030 1.06			
D1	.005	5			
E	.300	.300 .310 .325			
E1	.240	.250	.280	5	
е					
еA		300 BSC		6	
eВ	-	-	.430	7	
еC	.000	-	.060	7	
L	.115	.130	.150	4	



24-Pin Plastic DIP

Dimensions in Inches



NOTES:

- 1. CONTROLLING DIMENSION: INCH.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
- 3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR
- PROTRUSIONS TO BE .005 MINIMUM. 4 DIMENSIONS A, A1 & L ARE MEASURED WITH
- THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.

DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010

- 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED
- TO BE PERPENDICULAR TO DATUM -CeB AND eC ARE MEASURED AT THE LEAD TIPS
 with the LEADS UNCONSTRAINED.
- 8 N IS THE MAXIMUM NUMBER OF LEAD POSITIONS.
- 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
- 10 b2 MAXIMUM DIMENSIONS DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
- 11. DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

ГŲ		-H- GAGE		\ .015	-н-	
15		PLANE				17
						//
		PLANE				
		/ \ \ \ \ \ \ \ PLANE				
			-H-	-H- GAGE		

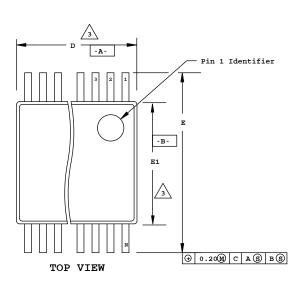
DETAIL A

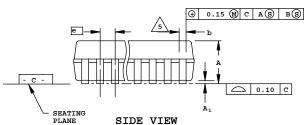
	1				
s Y M	I				
В 0				N T	
L	MIN.	NOM.	MAX.	E	
Α	-	-	.210	4	
A1	.015	-	-	4	
A 2	.115	.130	.195		
b	.014	.018	.022		
b1	.014	.018	.020		
b2	.045	.060	.070	10	
С	.008	.010	.014		
c1	.008	.010	.011		
D	1.230	1.230 1.250 1.280			
D1	.005			5	
E	.300	.310	.325	6	
E1	.240	.250	.280	5	
е	.100 BSC				
eА	.:	300 BSC	:	6	
еВ	-	-	.430	7	
еC	.000	-	.060	7	
L	.115	.130	.150		

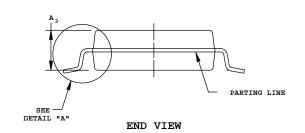


28-Pin SSOP Package

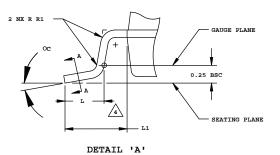
Dimensions in Millimeters

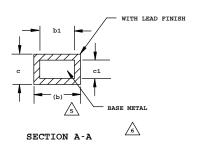






S Y	COMMON				
M B	DIMENSIONS				
O L	MIN.	NOM.	MAX.		
Α			2.0		
A	0.05	0.05			
A ₂	1.65	1.65 1.75 1.85			
b	0.22	0.22 - 0.38			
b ₁	0.22	0.30	0.33		
С	0.09		0.25		
Cı	0.09	0.15	0.21		
D	9.90	9.90 10.20 10.50			
E1	5.00	5.30	5.60		
е	0.65 BSC				
Е	7.40	7.80	8.20		
L	0.55	0.75	0.95		
L1	1.25 REF.				
N		28			
oc	0	4	8		
R1	0.09				





NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETERS.
- 2. DIMENSIONING & TOLERANCES PER ANSI.Y14.5M-1982.

"D" & "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DO INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.20mm PER SIDE.

4. TO BE DETERMINED AT THE SEATING PLANE

DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.
ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13mm TOTAL IN
EXCESS OF b DIMENSION AT MAXIMUM MATERIAL CONDITION.
DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION b BY MORE
THAN 0.07mm AT LEAST MATERIAL CONDITION.

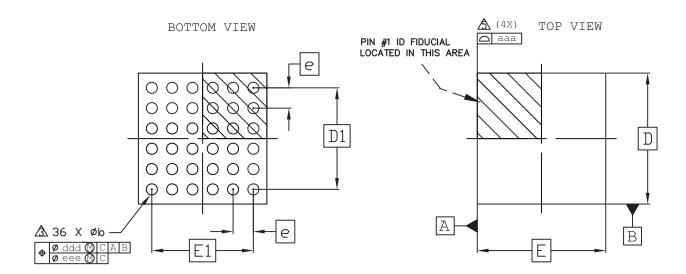
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 & 0.25mm FROM THE LEAD TIP

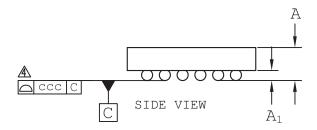
7. "N" IS THE NUMBER OF TERMINAL POSITIONS



36-Ball WLCS Package Option 3: LIFMD™

Dimensions in Millimeters





NOTES:

- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- \triangle PRIMARY DATUM $\boxed{\text{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- \triangle BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

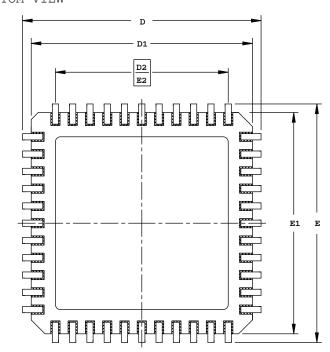
REF.	Min. Nom. Max.				
А	0.600				
A1	0.113	-	-		
b	0.188	0.218	0.248		
D	2.535 BSC				
E	2.583 BSC				
D1	2.00 BSC				
E1	2.00 BSC				
е	0.40 BSC				
aaa	0.030				
ccc	0.050				
ddd		0.050			
eee		0.015			
					

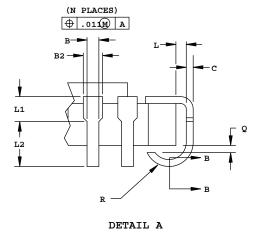


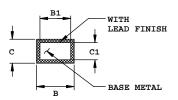
44-Pin JLCC Package

Dimensions in Inches

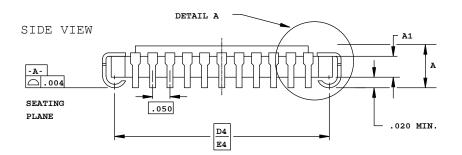
BOTTOM VIEW







SECTION B-B



NOTES:

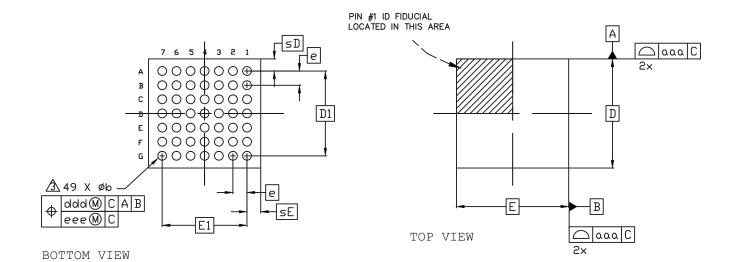
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- 3. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL.

S Y M	INCHES				
M B O L	MIN.		MAX.		
A	.115	1	.190		
A1	.065 REF				
В	.013	-	.023		
B1	.013	ı	.020		
B2	.022	-	.035		
С	.007	ı	.013		
C1	.007	ı	.010		
D/E	.675	.690	.700		
D1/E1	.620	ı	.660		
D2/E2	.500 BSC				
D4/E4	.630 BSC				
L	.005	ı	-		
L1	.020	-	-		
L2	.025	ı	-		
Q	.003	-	-		
R	.020	-	.040		
N		44			



49-Ball WLCS Package

Dimensions in Millimeters



M bbb C A A

SIDE VIEW

Notes:

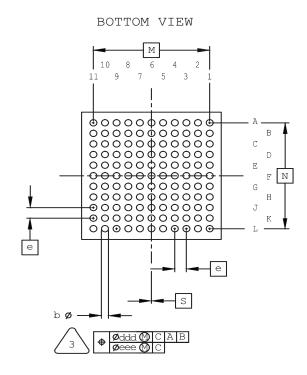
- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- riangle PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

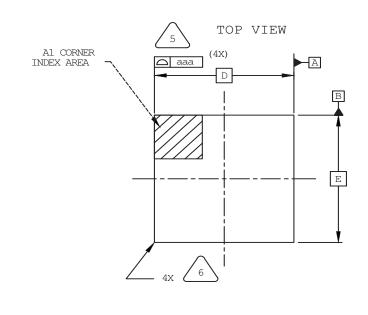
REF.	Min.	Nom.	Max.
A	_	0.600	
A1	0.167	0.199	0.232
b	0.239	0.266	0.319
D	3.055	3.106	3.155
E	3.125	3.185	3.225
D1	2.40 BSC		
E1	2.40 BSC		
е	0.40 BSC		
sD	0.353	_	0.383
sE	0.388	-	0.418
aaa	(0.030	
bbb	0.060		
ccc	0.050		
ddd	(0.015	
eee	(0.050	

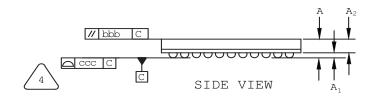


121-Ball csfBGA Package

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM $\overline{\mathbb{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

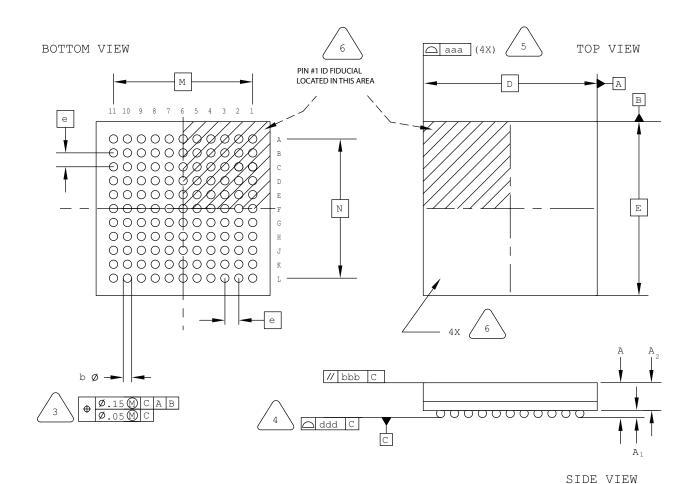


SYMBOL	MIN. NOM. MAX.			
А	1.00			
A1	0.15	0.24	-	
A2	_	0.66	ı	
D/E	6.00 BSC			
M/N	5.00 BSC			
S	0.00 BSC			
b	0.25 0.30 0.35			
е	0.50 BSC			
aaa	0.10			
bbb	0.10			
ccc	0.08			
ddd		0.15		
eee		0.05		



121-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

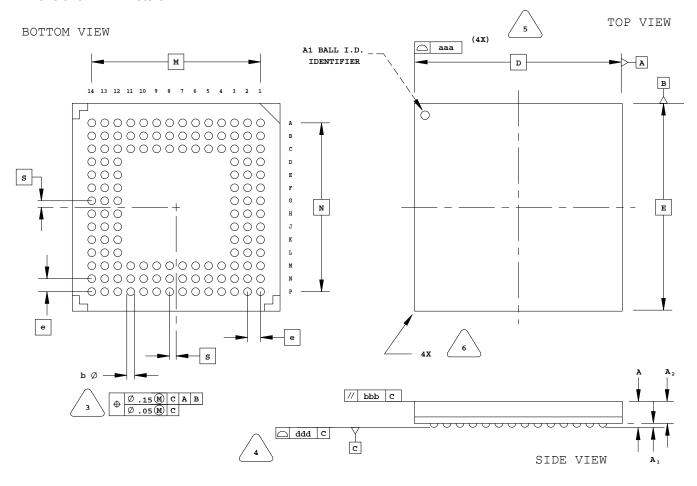


SYMBOL	MIN.	MIN. NOM.		
А			1.00	
A1	0.10 -		-	
A2			0.90	
D/E	5.00 BSC			
M/N	4.00 BSC			
b	0.20	0.25	0.30	
е	0.40 BSC			
aaa	-	-	0.10	
bbb	-	_	0.10	
ddd	-	-	0.10	



132-Ball csBGA Package Option 1: MachXO2, MachXO, LatticeXP2™

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

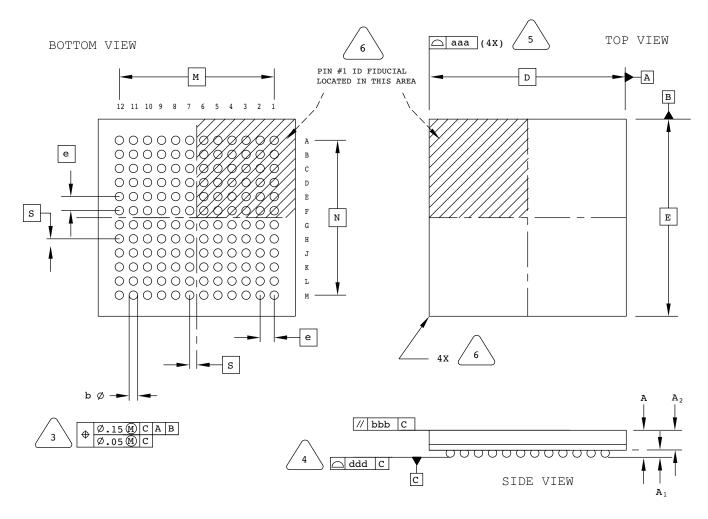


	Г		
SYMBOL	MIN.	NOM.	MAX.
A	0.90	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	8.00 BSC		
M/N	6.50 BSC		
s	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08



144-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

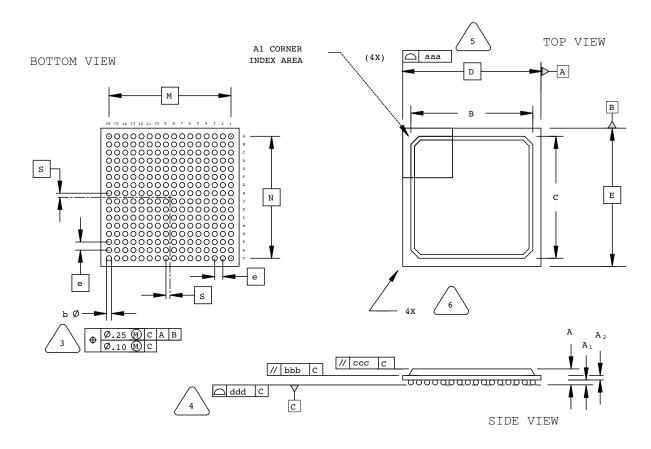


SYMBOL	MIN.	NOM.	MAX.
А	0.90	1.00	1.10
A1	0.15	-	ı
A2	-	-	0.85
D/E	7	.00 BSC	
M/N	5.50 BSC		
s	0	.25 BSC	
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08
		•	



256-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

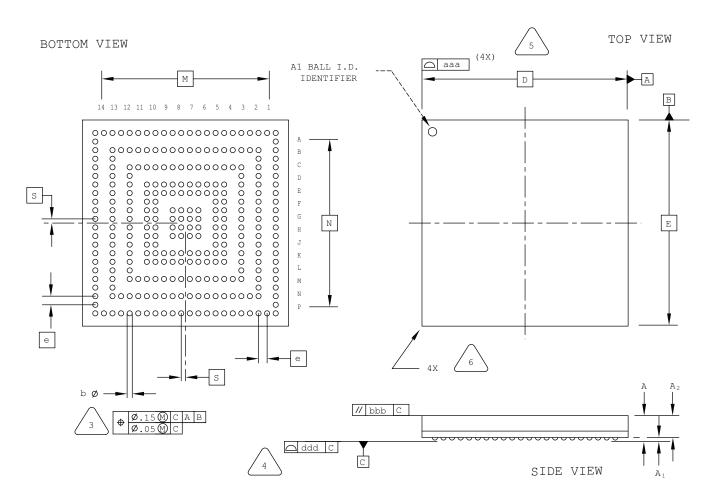


			-
SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
в/с	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	-	0.50 BSC	
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	_	0.25
ccc	-	_	0.35
ddd	-	_	0.20



284-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

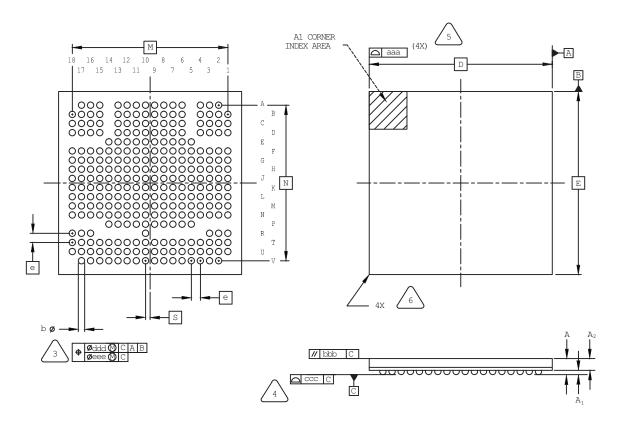


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.15	_	ı
A2	_	-	0.85
D/E	12.00 BSC		
M/N	10.50 BSC		
S	0.25 BSC		
b	0.25	0.31	0.37
е	0.50 BSC		
aaa	-	_	0.10
bbb	_	_	0.10
ddd	_	_	0.08



285-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

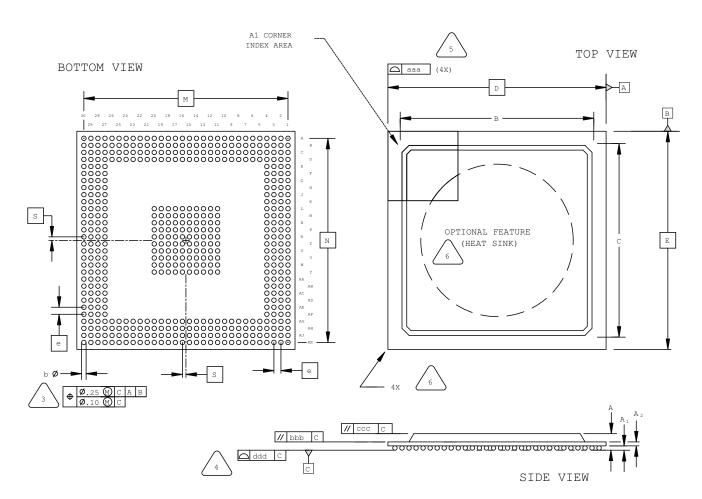


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.30
A1	0.15	_	_
A2	-	-	1.00
D/E	1	0.00 BSC	
M/N	8.50 BSC		
S	0.25 BSC		
b	0.25 0.30 0.35		0.35
е	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		



516-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

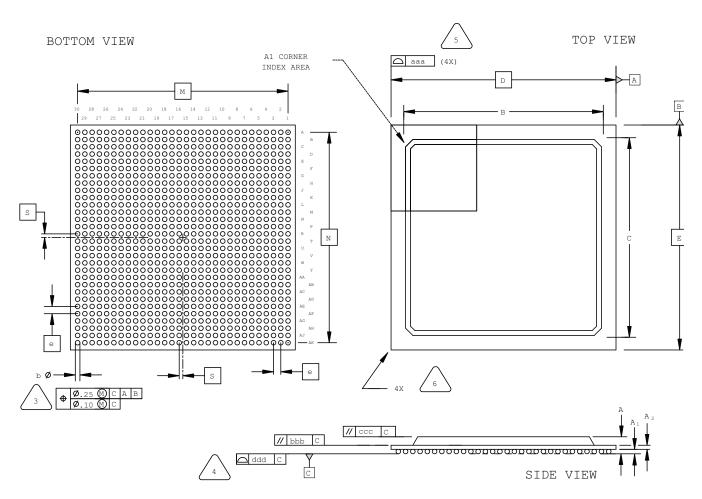


SYMBOL	MIN.	NOM.	MAX.
А	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	_	_	0.25
ccc	-	-	0.35
ddd	-	-	0.20



900-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

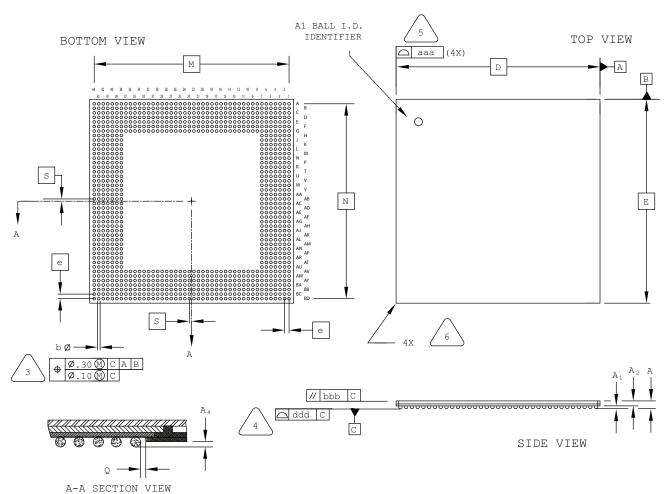


SYMBOL	MIN.	NOM.	MAX.
А	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	_	-	0.20
bbb	-	_	0.25
ccc	-		0.35
ddd	_	_	0.20



1036-Ball ftSBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

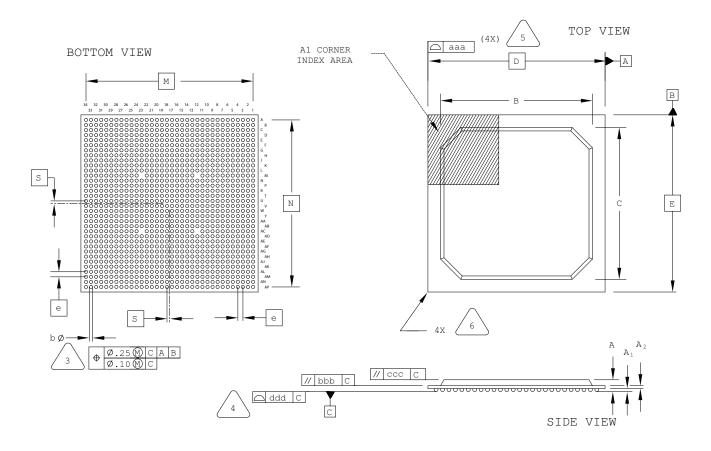


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.80
A1	0.40	0.55	0.70
A2	0.90	0.98	1.10
D/E	4.	5.00 BSC	
M/N	43.00 BSC		
S	0.50 BSC		
b	0.50	0.65	0.80
е	1.00 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.35
ddd	-	-	0.20



1152-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

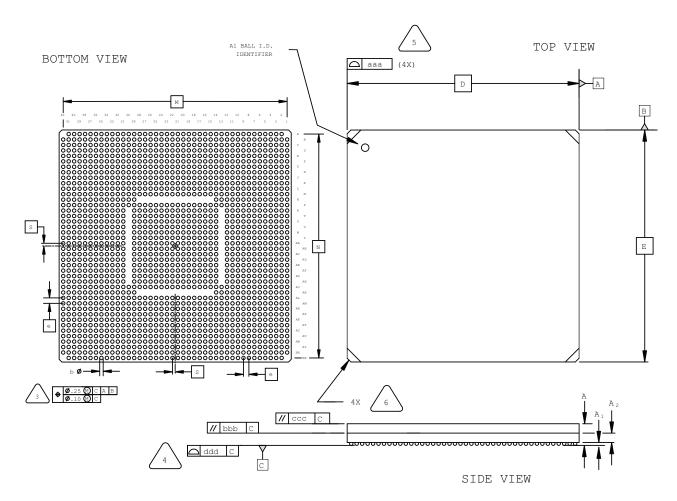
Note: Depopulated ball locations are M12, M23, AC12, and AC23.

SYMBOL	MIN.	NOM.	MAX.
А	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	3.	5.00 BSC	
M/N	33.00 BSC		
S		0.50 BSC	
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	_	_	0.20
bbb	_	_	0.25
ccc	-	-	0.35
ddd	_	_	0.20



1704-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY. PACKAGE BODY INCLUDES SUBSTRATE AND LID.





SYMBOL	MIN.	NOM.	MAX.
A	4.30	4.80	5.30
A1	0.30	0.50	0.70
A2	1.30	1.60	1.90
D/E	4:	2.50 BSC	
M/N	41.00 BSC		
S		0.50 BSC	
b	0.50	0.60	0.70
е	1.00 BSC		
aaa			0.20
bbb	İ	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20



Revision History

Date	Version	Change Summary
March 2017	5.4	Added ispMACH 4000 to 100-Pin TQFP Package Option 1: MachXO2, MachXO [™] , isp-MACH® 4000.
		Added 121-Ball caBGA Package (9x9 mm Body).
		Updated "32-Pin QFNS Package" headings to "32-Pin QFN Package".
		Added 32-Pin QFN Package Option 3: MachXO2 SG32C.
December 2016	5.3	Added 30-Ball WLSC Package.
December 2010	3.0	Added iCE40 UltraPlus and MachXO2 to 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2.
		Added 484-Ball caBGA Package.
		Updated 285-ball csfBGA package outline drawing.
		Added 36-Ball WLCS Package Option 3: LIFMD™.
June 2016	5.2	Fixed typo in 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2.
		Added 64-Ball ucfBGA Package.
		Added 80-Ball ctfBGA Package.
		Added 81-Ball csfBGA Package.
		Added 36-Ball ucfBGA Package: iCE40 Ultra.
February 2015	5.1	Updated 36-Ball ucBGA Package heading to 36-Ball ucBGA Package Option 1.
r obracily 2010		Updated 48-Pin QFN Package Option 2: L-ASC10 heading to 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra.
January 2015	5.0	Added 16-Ball WLCS Package Option 2: iCE40 UltraLite.
January 2015	5.0	Updated 16-Ball WLCS Package heading to 16-Ball WLCS Package Option 1: iCE40 LP.
0	4.9	Updated 48-Pin QFN Package heading and moved the section after 48-Pin QFN Package Option 1 (previously Option 2).
October 2014	4.8	Removed 20-Ball WLCS Package.
	4.7	Updated 121-Ball csfBGA Package. Revised M/N dimension.
September 2014	4.6	Updated 84-Pin QFN Package. Revised pin numbers from A36 and B27 to A37 and B28.
		Updated 16-Ball WLCS Package. Changed second E to e in REF. column.
		Updated 36-Ball WLCS Package Option 1: iCE40 Ultra heading.
		Added 36-Ball WLCS Package Option 2: MachXO3.
		Added 81-Ball WLCS Package.
		Added 121-Ball csfBGA Package.
August 2014	4.5	Added 256-Ball csfBGA Package.
/ laguet = 0 · ·	7.0	Added 324-Ball caBGA Package.
		Added 324-Ball csfBGA Package.
		Added 400-Ball caBGA Package.
		Updated 84-Pin QFN Package. Revised dimension "b" maximum value.
		Updated 256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2. Revised dimension "A" values.